

FB-e18LDW

搭載特殊搬送功能
對應雷射半導體的焊線機

*Wire Bonder for laser diode
with special transfer apparatus*

FB-e18LDW 的特長

- * 搭載新型高速辨識機構
- * 實現低震動的制震控制XY平台
- * 超小型無反作用力的線夾
- * 實現低慣性的高速焊頭
- * 搭載雙頻超音波振動子
- * 2色LED照明
- * 搭載對應CAN型雷射二極體的專用搬送機構
- * 焊線後另行收納於不同的承載盤

Features of FB-e18LDW

- * New unit with high-speed recognition
- * Newly developed XY table achieved low vibration
- * Recoilless micro wire cut clamp
- * High-speed bonding head achieved low inertia
- * Dual frequency US transducer
- * Two color LED illumination
- * Dedicated transfer apparatus to CAN type laser diode devices
- * Stored in another tray after bonding

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■主要規格

焊線性能	
細間距對應性	35 μ m
焊線反覆精度 (不含自檢精度)	$\pm 2.5 \mu$ m (3 σ) ※依對象品種可能需要精度安定用組件
焊線範圍	56mm $\times$ 80mm
辨識系統	高速、高精度畫像處理引擎 1/3"CCD照相機 可編程對焦鏡頭
線弧(使用線徑 25 μ m時)	
線長	最大8.0mm
線弧高度	標準模式/100 μ m FJ線弧/65 μ m
線飄移量	線長1%以下
生產性	
焊線時間	45msec/每條線
辨識時間	100msec/2點 (□5mm晶片時)
LEAD定位時間	11msec/Lead (在螢幕中顯示有3個 Lead時)
對應搬送系統	
適用承載盤尺寸	172.5mm $\times$ 156mm $\times$ 14~25mm
儲存數	最多5個承載盤 (可能因承載盤形狀不同而有所出入)
操作性	
螢幕	2台
操作面板	使用頻率高的專用開關 三鍵滑鼠操作
外部介面	
	HSMS標準裝備 USB記憶體
設備需求	
壓縮空氣	0.3~0.97MPa (3.1~9.9Kgf/cm ²) 40NL/min
真空	-53.32KPa以下 (400mm/Hg以上)
電源	AC200V、50/60Hz、 $\pm 5\%$ 以下 (AC100、220、240V 選配)
消耗電力	約1.5KVA
外觀尺寸	W1365 $\times$ D1330 $\times$ H1781mm (若包含警示燈, 則高度為2000mm)
重量	650kg

■SPECIFICATIONS

Bonding	
Fine Pad Pitch Capability	35 μ m
Repeatability of Bonding Accuracy (Excluding Self-Teach Accuracy)	$\pm 2.5 \mu$ m (3 σ) ※Special kit for accuracy stability may be required depending on devices.
Bonding Area	56mm $\times$ 80mm
Recognition System	High Speed·High Accuracy Process Engine 1/3"CCD Camera Programmable focus lens
Looping (In the case of wire diameter 25 μ m)	
Wire Length	8.0mm in max
Loop Height	Standard mode 100 μ m FJ Loop 65 μ m
Wire Curl	Less than 1% of the wire length
Productivity	
Bonding Time	45msec/wire
Recognition Time	100msec/2 points (□5mm Chip)
Lead Locate(VLL)Time	11msec/lead (In the case of 3 leads within a monitor)
Indexing System	
Appropriate dimension of tray	172.5mm $\times$ 156mm $\times$ 14~25mm
No.of Tray to Stock	5 tray maximum (Stockable number of tray depends on the shape of tray.)
Operability	
Monitor	2 sets
Operation Panel	Operation by mouse with 3 buttons
External Interface	
	HSMS USB memory
Utility	
Air	0.3~0.97MPa (3.1~9.9Kgf/cm ²) 40NL/min
Vacuum	-53.32KPa or less (400mm/Hg or more)
Power Source	AC200V、50/60Hz、 $\pm 5\%$ or less (AC100、220、240V option)
Power Consumption	Approx. 1.5KVA
Overall Dimensions	W1365 $\times$ D1330 $\times$ H1781m (H2000mm, Including indicating lamp)
Weight	650kg



使用安全上的注意事項：為保障客戶能安全使用商品，煩請於使用前務必詳讀「使用說明書」

●型錄上的注意事項：型錄中所刊載的商品規格與外觀，有可能因改良而無預警的變更，請見諒。



CAUTION FOR SAFE: Please read surely INSTRUCTION MANUAL before operate.

●Specification is subject to change without prior notice for improvement.



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